

SBOS057A - OCTOBER 1996 - REVISED FEBRUARY 2007

SINGLE-SUPPLY OPERATIONAL AMPLIFIERS *MicroAmplifier*™ Series

FEATURES

• MICRO-SIZE, MINIATURE PACKAGES:

Single: SOT23-5, SO-8Dual: MSOP-8, SO-8

Quad: SSOP-16 (Obsolete)
 LOW OFFSET VOLTAGE: 750μV max

• WIDE SUPPLY RANGE:

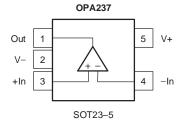
Single Supply: +2.7V to +36VDual Supply: ±1.35V to ±18V

• LOW QUIESCENT CURRENT: 350μV max

WIDE BANDWIDTH: 1.5MHz

APPLICATIONS

- BATTERY-POWERED INSTRUMENTS
- PORTABLE DEVICES
- PCMCIA CARDS
- MEDICAL INSTRUMENTS
- TEST EQUIPMENT

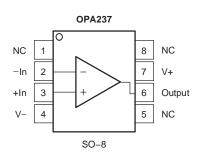


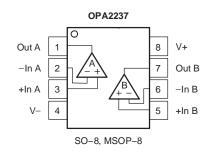
DESCRIPTION

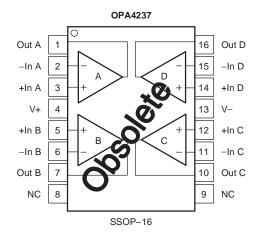
The OPA237 op amp family is one of Texas Instruments' MicroAmplifier™ series of miniature products. In addition to small size, these devices feature low offset voltage, low quiescent current, low bias current, and a wide supply range. Single, dual, and quad versions have identical specifications for maximum design flexibility. They are ideal for single-supply, battery-operated, and space-limited applications, such as PCMCIA cards and other portable instruments.

OPA237 series op amps can operate from either single or dual supplies. When operated from a single supply, the input common-mode range extends below ground and the output can swing to within 10mV of ground. Dual and quad designs feature completely independent circuitry for lowest crosstalk and freedom from interaction.

Single, dual, and quad are offered in space-saving surface-mount packages. The single version is available in the ultra-miniature 5-lead SOT23-5 and SO-8 surface-mount. The dual version comes in a miniature MSOP-8 and SO-8 surface-mount. The quad version is obsolete. MSOP-8 has the same lead count as a SO-8 but half the size. The SOT23-5 is even smaller at one-fourth the size of an SO-8. All are specified for -40°C to +85°C operation. A macromodel is available for design analysis.









Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

MicroAmplifier is a trademark of Texas Instruments. All other trademarks are the property of their respective owners.





ABSOLUTE MAXIMUM RATINGS(1)

Supply Voltage, V+ to V	36V
Input Voltage	. (V-) -0.7V to (V+) +0.7V
Output Short-Circuit(2)	Continuous
Operating Temperature Range	–55°C to +125°C
Storage Temperature Range	–55°C to +125°C
Junction Temperature Range	+150°C

(1) Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those specified is not implied.

(2) Short circuit to ground, one amplifier per package.



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe

proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

PACKAGE/ORDERING INFORMATION(1)

PRODUCT	PACKAGE-LEAD	PACKAGE DRAWING	PACKAGE MARKING
Single OPA237NA	SOT23-5	DBV	A37A
OPA237UA	SO-8	D	OPA237UA
Dual OPA2237EA	MSOP-8	DGK	B37A
OPA2237UA	SO-8	D	OPA2237UA
Quad ⁽²⁾ OPA4237UA	SSOP-16	DBQ	OPA4237UA

⁽¹⁾ For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at www.ti.com.

⁽²⁾ Quad version is obsolete.

OPA237



ELECTRICAL CHARACTERISTICS: $V_S = +5V$

Boldface limits apply over the specified temperature range, $T_A = -40^{\circ}C$ to $+85^{\circ}C$.

At T_A = +25°C, V_S = +5V, R_L = 10k Ω , connected to $V_S/2$, unless otherwise noted.

			OPA237UA, NA OPA2237UA, EA OPA4237UA				
PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS		
OFFSET VOLTAGE Input Offset Voltage vs Temperature(1) vs Power Supply (PSRR) Channel Separation (dual and quad)	V_{CM} = 2.5V Specified Temperature Range V_S = +2.7V to +36V		±250 ± 2 10 0.5	±750 ± 5 30	μV μ V/°C μV/V μV/V		
INPUT BIAS CURRENT Input Bias Current(2) Input Offset Current	$V_{CM} = 2.5V$ $V_{CM} = 2.5V$		-10 ±0.5	-40 ±10	nA nA		
NOISE Input Voltage Noise, f = 0.1 to 10Hz Input Voltage Noise Density, f = 1kHz Current Noise Density, f = 1kHz			1 28 60		μV _{PP} nV/√Hz fA/√Hz		
INPUT VOLTAGE RANGE Common-Mode Voltage Range Common-Mode Rejection Ratio	$V_{CM} = -0.2V \text{ to } 3.5V$	-0.2 78	86	(V+) -1.5	V dB		
INPUT IMPEDANCE Differential Common-Mode			5 • 10 ⁶ 4 5 • 10 ⁹ 2		Ω pF Ω pF		
OPEN-LOOP GAIN Open-Loop Voltage Gain	V _O = 0.5V to 4V	80	88		dB		
FREQUENCY RESPONSE Gain-Bandwidth Product Slew Rate Settling Time, 0.1% 0.01%	G = 1 $G = -1$, 3V Step, $C_L = 100$ pF $G = -1$, 3V Step, $C_L = 100$ pF		1.4 0.5 11 16		MHz V/μs μs μs		
OUTPUT Voltage Output, Positive	$R_L = 100 k\Omega \text{ to Ground}$ $R_L = 100 k\Omega \text{ to Ground}$ $R_L = 100 k\Omega \text{ to } 2.5 \text{V}$ $R_L = 100 k\Omega \text{ to } 2.5 \text{V}$ $R_L = 10 k\Omega \text{ to } 2.5 \text{V}$ $R_L = 10 k\Omega \text{ to } 2.5 \text{V}$ $R_L = 10 k\Omega \text{ to } 2.5 \text{V}$	(V+) -1 0.01 (V+) -1 0.12 (V+) -1 0.5	(V+) -0.75 0.001 (V+) -0.75 0.04 (V+) -0.75 0.35 -10/+4 ical Characterist	ic Curves	V V V V V mA		
POWER SUPPLY Specified Operating Voltage Operating Range Quiescent Current (per amplifier)		+2.7	+5 170	+36 350	V V μΑ		
TEMPERATURE RANGE Specified Range Operating Range Storage Range Thermal Resistance, $\theta_{\rm JA}$		-40 -55 -55		+85 +125 +125	°C °C		
SOT23-5 MSOP-8 SSOP-16 (Obsolete) SO-8			200 150 150 150		°C/W °C/W °C/W		

⁽¹⁾ Specified by wafer-level test to 95% confidence.(2) Positive conventional current flows into the input terminals.



ELECTRICAL CHARACTERISTICS: $V_S = +2.7V$ Boldface limits apply over the specified temperature range, $T_A = -40^{\circ}C$ to +85°C.

At T_A = +25°C, V_S = +2.7V , R_L = 10k Ω , connected to $V_S/2$, unless otherwise noted.

			OPA237UA, NA OPA2237UA, EA OPA4237UA					
PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS			
OFFSET VOLTAGE								
Input Offset Voltage	$V_{CM} = 1V$		±250	±750	μV			
vs Temperature ⁽¹⁾	Specified Temperature Range		±2	±5	μ ۷/ °C			
vs Power Supply (PSRR)	$V_S = +2.7V \text{ to } +36V$		10	30	μV/V			
Channel Separation (dual and quad)			0.5		μV/V			
INPUT BIAS CURRENT								
Input Bias Current(2)	$V_{CM} = 1V$		-10	-40	nA			
Input Offset Current	$V_{CM} = 1V$		±0.5	±10	nA			
NOISE								
Input Voltage Noise, f = 0.1 to 10Hz			1		μV_{PP}			
Input Voltage Noise Density, f = 1kHz			28		nV/√Hz			
Current Noise Density, f = 1kHz			60		fA/√Hz			
INPUT VOLTAGE RANGE								
Common-Mode Voltage Range		-0.2		(V+) -1.5	V			
Common-Mode Rejection Ratio	$V_{CM} = -0.2V$ to 1.2V	75	85		dB			
INPUT IMPEDANCE								
Differential			5 • 10 ⁶ 4		Ω pF			
Common-Mode			5 • 10 ⁹ 2		Ω pF			
OPEN-LOOP GAIN								
Open-Loop Voltage Gain	$V_{O} = 0.5V \text{ to } 1.7V$	80	88		dB			
FREQUENCY RESPONSE								
Gain-Bandwidth Product			1.2		MHz			
Slew Rate	G = 1		0.5		V/μs			
Settling Time, 0.1%	$G = -1$, 1V Step, $C_L = 100pF$		5		μs			
0.01%	$G = -1$, 1V Step, $C_L = 100pF$		8		μs			
OUTPUT								
Voltage Output, Positive	$R_L = 100k\Omega$ to Ground	(V+) -1	(V+) -0.75		V			
Negative	$R_L = 100k\Omega$ to Ground	0.01	0.001		V			
Positive	$R_L = 100k\Omega$ to 1.35V	(V+) -1	(V+) -0.75		V			
Negative	$R_L = 100k\Omega$ to 1.35V	0.06	0.02		V			
Positive	$R_L = 10k\Omega$ to 1.35V	(V+) -1	(V+) -0.75		V			
Negative	$R_L = 10k\Omega$ to 1.35V	0.3	0.2		V			
Short-Circuit Current			-5/+3.5	_	mA			
Capacitive Load Drive (stable operation)		See Typi	cal Characterist	ic Curves				
POWER SUPPLY								
Specified Operating Voltage			+2.7		V			
Operating Range		+2.7		+36	V			
Quiescent Current (per amplifier)			160	350	μΑ			
TEMPERATURE RANGE								
Specified Range		-40 55		+85	°C			
Operating Range		-55 -55		+125	°C			
Storage Range		-55		+125	°C			
Thermal Resistance, θ_{JA}			000		00044			
SOT23-5			200		°C/W			
MSOP-8			150		°C/W			
SSOP-16 (Obsolete)			150		°C/W			
SO-8			150		°C/W			

⁽¹⁾ Specified by wafer-level test to 95% confidence.(2) Positive conventional current flows into the input terminals.

OPA237



ELECTRICAL CHARACTERISTICS: $V_S = \pm 15V$

Boldface limits apply over the specified temperature range, $T_A = -40^{\circ}C$ to $+85^{\circ}C$.

At T_A = +25°C, V_S = ±15V , R_L = 10k Ω , connected to $V_S/2$, unless otherwise noted.

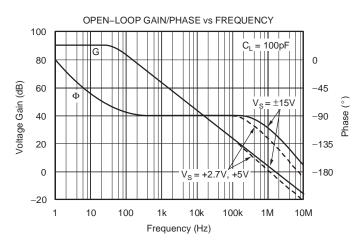
			OPA237UA, NA OPA2237UA, EA OPA4237UA					
PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS			
OFFSET VOLTAGE								
Input Offset Voltage	$V_{CM} = 0V$		±350	±950	μV			
vs Temperature ⁽¹⁾	Specified Temperature Range		±2.5	±7	μ V/ °C			
vs Power Supply (PSRR)	$V_{S} = \pm 1.35 \text{V to } \pm 18 \text{V}$		10	30	μV/V			
Channel Separation (dual and quad)	9		0.5		μV/V			
INPUT BIAS CURRENT								
Input Bias Current(2)	$V_{CM} = 0V$		-8.5	-40	nA			
Input Offset Current	$V_{CM} = 0V$		±0.5	±10	nA			
NOISE								
Input Voltage Noise, f = 0.1 to 10Hz			1		μVpp			
Input Voltage Noise Density, f = 1kHz			28		nV/√ Hz			
Current Noise Density, f = 1kHz			60		fA/√ Hz			
INPUT VOLTAGE RANGE								
Common-Mode Voltage Range		(V-)-0.2		(V+) -1.5	V			
Common-Mode Rejection Ratio	$V_{CM} = -15V$ to 13.5V	80	90		dB			
INPUT IMPEDANCE	*							
Differential			5 • 10 ⁶ 4		Ω pF			
Common-Mode			5 • 10 ⁹ 2		Ω pF			
OPEN-LOOP GAIN								
Open-Loop Voltage Gain	$V_O = -14V$ to 13.8V	80	88		dB			
FREQUENCY RESPONSE								
Gain-Bandwidth Product			1.5		MHz			
Slew Rate	G = 1		0.5		V/μs			
Settling Time, 0.1%	G = -1, 10V Step, C _L = 100pF		18		μs			
0.01%	$G = -1$, 10V Step, $C_L = 100pF$		21		μs			
OUTPUT								
Voltage Output, Positive	$R_L = 100k\Omega$	(V+) -1.2	(V+) -0.9		V			
Negative	$R_L = 100k\Omega$	(V-) +0.5	(V-) +0.3		V			
Positive	$R_L = 10k\Omega$	(V+) -1.2	(V+) -0.9		V			
Negative	$R_L = 10k\Omega$	(V-) +1	(V-) +0.85		V			
Short-Circuit Current			-8/+4.5		mA			
Capacitive Load Drive (stable operation)		See Typi	cal Characterist	tic Curves				
POWER SUPPLY								
Specified Operating Range			±15		V			
Operating Range		±1.35		±18	V			
Quiescent Current (per amplifier)			±200	±475	μΑ			
TEMPERATURE RANGE								
Specified Range		-40		+85	°C			
Operating Range		-55		+125	°C			
Storage Range		-55		+125	°C			
Thermal Resistance, θ_{JA}								
SOT23-5			200		°C/W			
MSOP-8			150		°C/W			
SSOP-16 (Obsolete)			150		°C/W			
SO-8			150		°C/W			

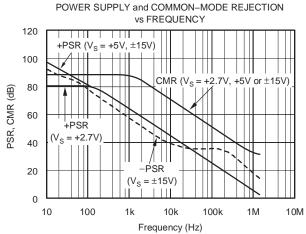
⁽¹⁾ Specified by wafer-level test to 95% confidence.(2) Positive conventional current flows into the input terminals.

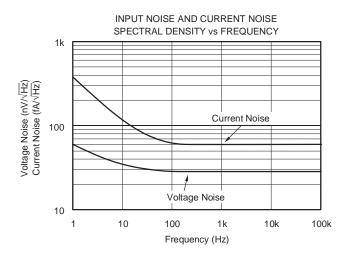


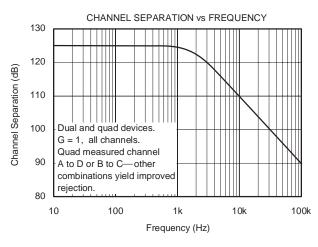
TYPICAL CHARACTERISTICS

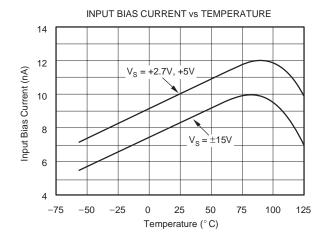
At $T_A = +25$ °C and $R_L = 10k\Omega$, unless otherwise noted.

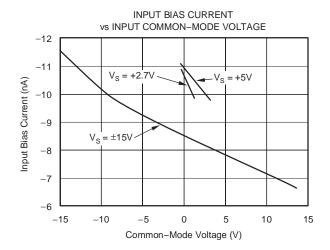








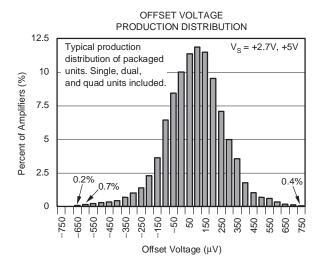


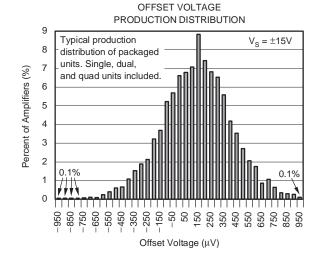


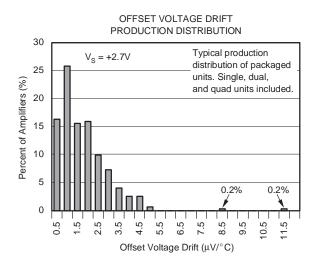


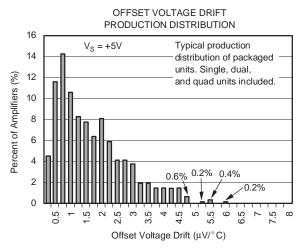
TYPICAL CHARACTERISTICS (Continued)

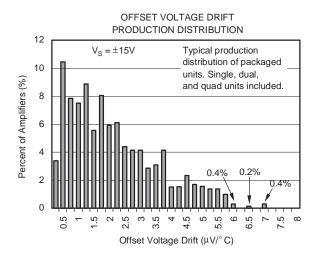
At $T_A = +25$ °C and $R_I = 10k\Omega$, unless otherwise noted.

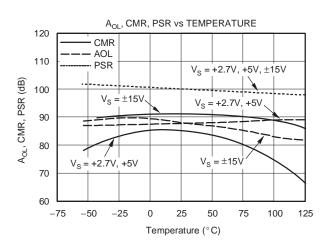








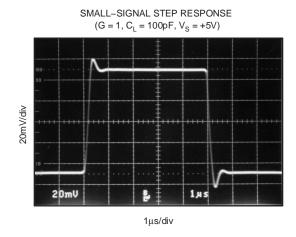


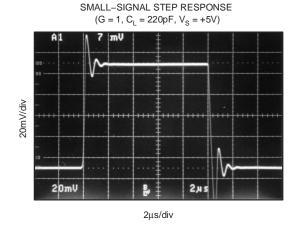


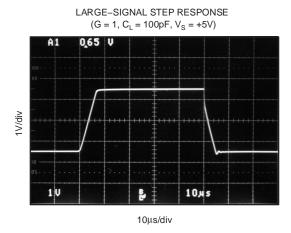


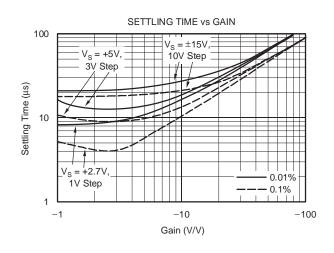
TYPICAL CHARACTERISTICS (Continued)

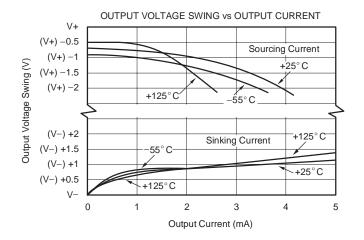
At T_A = +25°C and R_L = 10k Ω , unless otherwise noted.

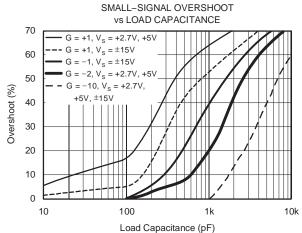








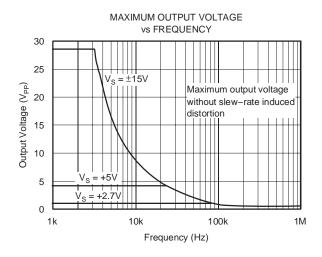


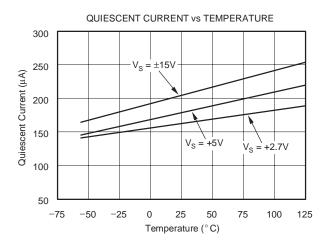


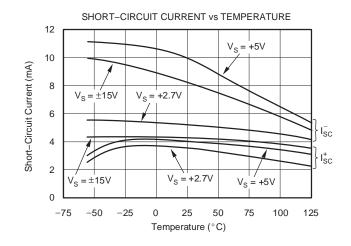


TYPICAL CHARACTERISTICS (Continued)

At $T_A = +25^{\circ}C$ and $R_L = 10k\Omega$, unless otherwise noted.







APPLICATION INFORMATION

OPA237 series op amps are unity-gain stable and suitable for a wide range of general-purpose applications. Power supply pins should be bypassed with 10nF ceramic capacitors.

OPERATING VOLTAGE

OPA237 series op amps operate from single ($\pm 2.7V$ to $\pm 36V$) or dual ($\pm 1.35V$ to $\pm 18V$) supplies with excellent performance. Most behavior remains unchanged throughout the full operating voltage range. Parameters which vary significantly with operating voltage are shown in typical performance curves. Specifications are production tested with $\pm 2.7V$, $\pm 5V$, and $\pm 15V$ supplies.

OUTPUT CURRENT AND STABILITY

OPA237 series op amps can drive large capacitive loads. However, under certain limited output conditions any op amp may become unstable. Figure 1 shows the region where the OPA237 has a potential for instability. These load conditions are rarely encountered, especially for single supply applications. For example, take the case when a +5V supply with a $10k\Omega$ load to $V_S/2$ is used.

OPA237 series op amps remain stable with capacitive loads up to 4,000pF, if sinking current and up to 10,000pF, if sourcing current. Furthermore, in single-supply applications where the load is connected to ground, the op amp is only sourcing current, and as shown Figure 1, can drive 10,000pF with output currents up to 1.5mA.

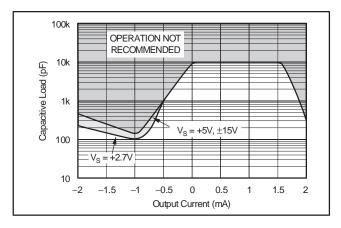


Figure 1. Stability-Capacitive Load vs Output
Current

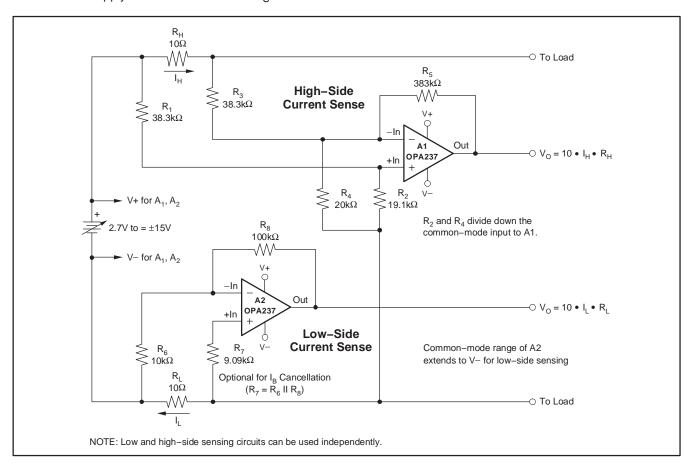


Figure 2. Low and High-Side Battery Current Sensing

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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
OPA2237EA/250	ACTIVE	VSSOP	DGK	8	250	RoHS & Green	NIPDAUAG	Level-2-260C-1 YEAR		B37A	Samples
OPA2237EA/2K5	ACTIVE	VSSOP	DGK	8	2500	RoHS & Green	Call TI NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	B37A	Samples
OPA2237UA	ACTIVE	SOIC	D	8	75	RoHS & Green	NIPDAU	Level-3-260C-168 HR		OPA 2237UA	Samples
OPA2237UA/2K5	ACTIVE	SOIC	D	8	2500	RoHS & Green	NIPDAU	Level-3-260C-168 HR		OPA 2237UA	Samples
OPA2237UAE4	ACTIVE	SOIC	D	8	75	TBD	Call TI	Call TI			Samples
OPA237NA/250	ACTIVE	SOT-23	DBV	5	250	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 70	A37A	Samples
OPA237NA/250E4	LIFEBUY	SOT-23	DBV	5	250	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 70	A37A	
OPA237NA/3K	ACTIVE	SOT-23	DBV	5	3000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 70	A37A	Samples
OPA237NA/3KE4	LIFEBUY	SOT-23	DBV	5	3000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 70	A37A	
OPA237UA	ACTIVE	SOIC	D	8	75	RoHS & Green	NIPDAU	Level-3-260C-168 HR	-40 to 70	OPA 237UA	Samples
OPA237UA/2K5	ACTIVE	SOIC	D	8	2500	RoHS & Green	NIPDAU	Level-3-260C-168 HR	-40 to 70	OPA 237UA	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.



PACKAGE OPTION ADDENDUM

www.ti.com 23-Dec-2023

- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
OPA2237EA/250	VSSOP	DGK	8	250	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
OPA2237EA/2K5	VSSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
OPA2237UA/2K5	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
OPA237NA/250	SOT-23	DBV	5	250	178.0	9.0	3.3	3.2	1.4	4.0	8.0	Q3
OPA237NA/3K	SOT-23	DBV	5	3000	178.0	9.0	3.3	3.2	1.4	4.0	8.0	Q3
OPA237UA/2K5	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1



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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
OPA2237EA/250	VSSOP	DGK	8	250	366.0	364.0	50.0
OPA2237EA/2K5	VSSOP	DGK	8	2500	366.0	364.0	50.0
OPA2237UA/2K5	SOIC	D	8	2500	356.0	356.0	35.0
OPA237NA/250	SOT-23	DBV	5	250	180.0	180.0	18.0
OPA237NA/3K	SOT-23	DBV	5	3000	180.0	180.0	18.0
OPA237UA/2K5	SOIC	D	8	2500	356.0	356.0	35.0

PACKAGE MATERIALS INFORMATION

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TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
OPA2237UA	D	SOIC	8	75	506.6	8	3940	4.32
OPA237UA	D	SOIC	8	75	506.6	8	3940	4.32



SMALL OUTLINE TRANSISTOR



NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
 2. This drawing is subject to change without notice.
 3. Reference JEDEC MO-178.

- 4. Body dimensions do not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.25 mm per side.
- 5. Support pin may differ or may not be present.



SMALL OUTLINE TRANSISTOR



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE TRANSISTOR



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.





SMALL OUTLINE INTEGRATED CIRCUIT



NOTES:

- 1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 [0.15] per side.
- 4. This dimension does not include interlead flash.
- 5. Reference JEDEC registration MS-012, variation AA.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



DGK (S-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 per end.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.50 per side.
- E. Falls within JEDEC MO-187 variation AA, except interlead flash.



DGK (S-PDSO-G8)

PLASTIC SMALL OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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